



Hybrid Manufacturing

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Message from the Guest Editors

Dear Colleagues,

Recent growth in engineering knowledge and technologies has evoked rapid advancement in multifarious fields. However, the unavailability of suitable materials and manufacturing processes has impeded such advancements. The advantages of the superior characteristics of a material are often mitigated by added processing complexity and manufacturing costs. Hybrid manufacturing attempts to alleviate these difficulties by accentuating the strengths of individual processing avenues, while suppressing the drawbacks. For example, chemical–mechanical polishing enables the planarization of hard wafer materials by a chemical reaction with slurry while enhancing both planarization quality and throughput. Laser-assisted cold spray enables the deposition of metals of high specific stiffness with minimal porosity via the pre- or post-heating of a substrate material.

In this context, this issue focuses on the recent advances in hybrid manufacturing. The collection of state of the art hybrid manufacturing processes around the world should provide the current trends of hybrid manufacturing and help chart its future direction.





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Message from the Editor-in-Chief

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